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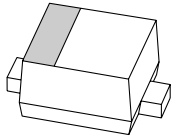
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BAP51-02

General purpose PIN diode

Rev. 03 — 2 January 2008

Product data sheet

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NXP Semiconductors

General purpose PIN diode

BAP51-02

FEATURES

- Low diode capacitance
- Low diode forward resistance.

APPLICATIONS

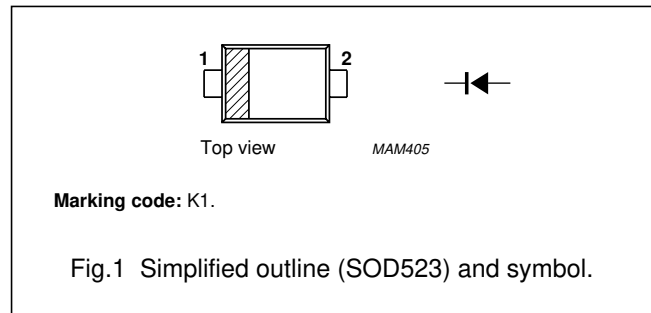
- General RF applications.

DESCRIPTION

General purpose PIN diode in a SOD523 ultra small SMD plastic package.

PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1 | cathode |
| 2 | anode |



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|-----------|----------------------------|----------------------|------|------|------|
| V_R | continuous reverse voltage | | – | 60 | V |
| I_F | continuous forward current | | – | 50 | mA |
| P_{tot} | total power dissipation | $T_s = 90\text{ °C}$ | – | 715 | mW |
| T_{stg} | storage temperature | | –65 | +150 | °C |
| T_j | junction temperature | | –65 | +150 | °C |

ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|--------|--------------------------|--|------|------|------|----------|
| V_F | forward voltage | $I_F = 50\text{ mA}$ | – | 0.95 | 1.1 | V |
| V_R | reverse voltage | $I_R = 10\text{ }\mu\text{A}$ | 50 | – | – | V |
| I_R | reverse current | $V_R = 50\text{ V}$ | – | – | 100 | nA |
| C_d | diode capacitance | $V_R = 0; f = 1\text{ MHz}$ | – | 0.4 | – | pF |
| | | $V_R = 1\text{ V}; f = 1\text{ MHz}$ | – | 0.3 | 0.55 | pF |
| | | $V_R = 5\text{ V}; f = 1\text{ MHz}$ | – | 0.2 | 0.35 | pF |
| r_D | diode forward resistance | $I_F = 0.5\text{ mA}; f = 100\text{ MHz}; \text{note 1}$ | – | 5.5 | 9 | Ω |
| | | $I_F = 1\text{ mA}; f = 100\text{ MHz}; \text{note 1}$ | – | 3.6 | 6.5 | Ω |
| | | $I_F = 10\text{ mA}; f = 100\text{ MHz}; \text{note 1}$ | – | 1.5 | 2.5 | Ω |

Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

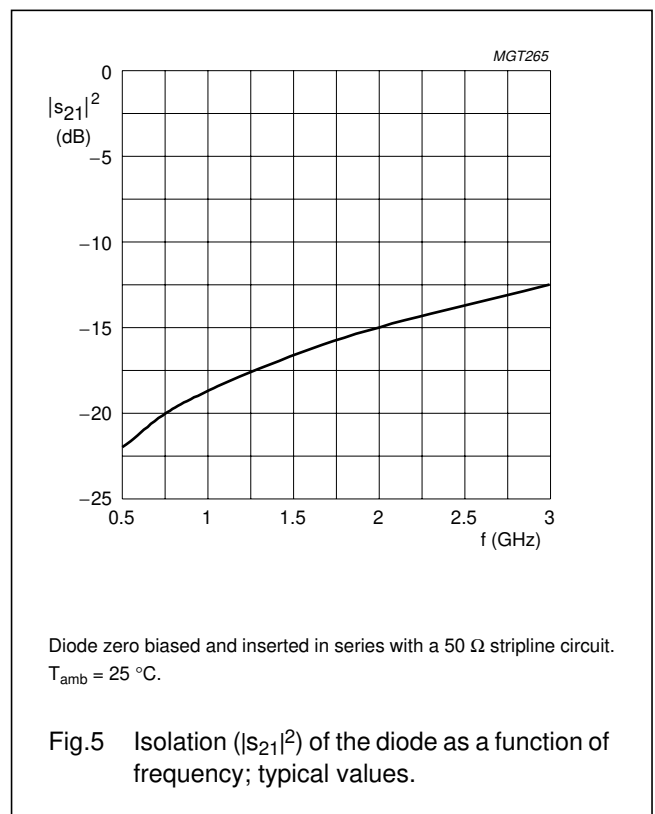
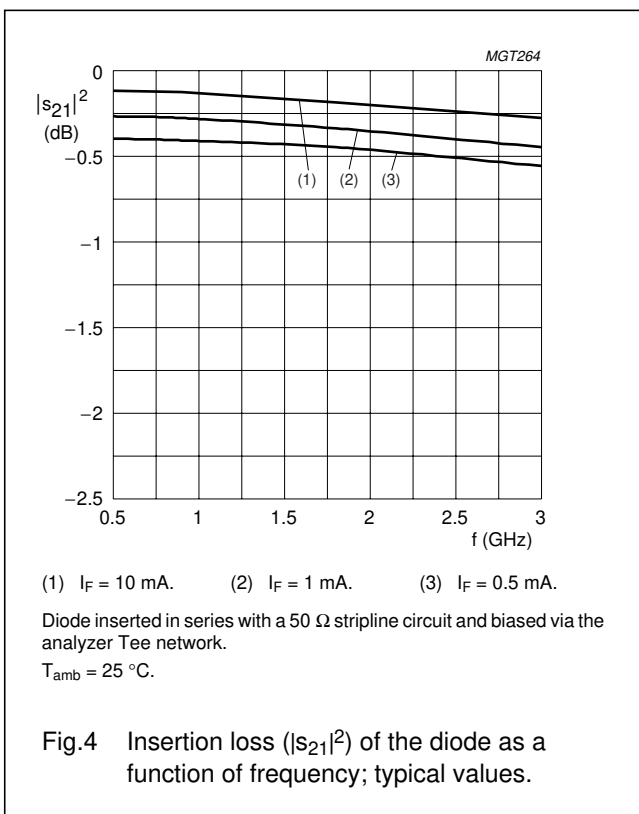
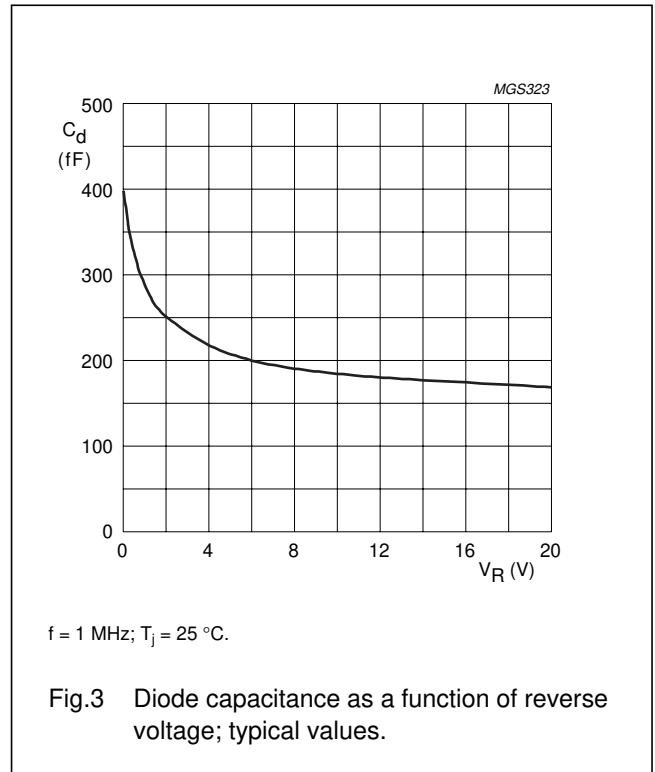
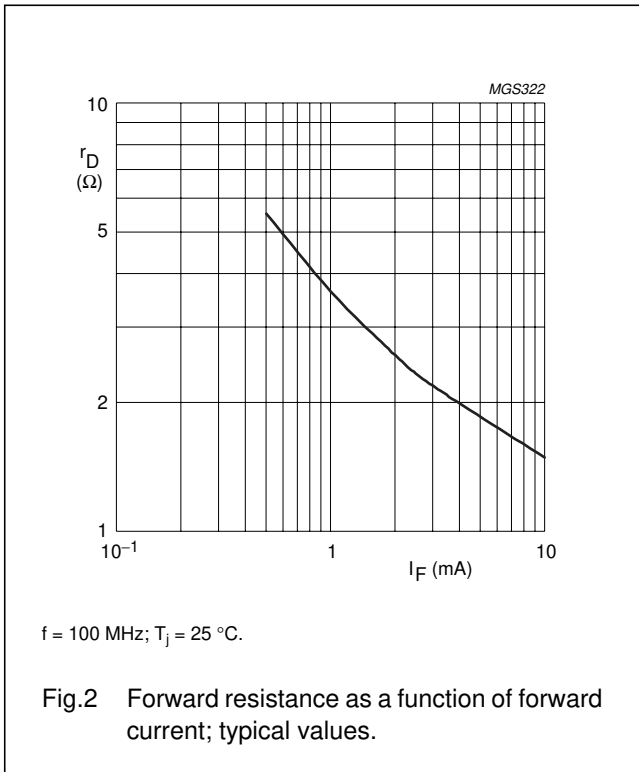
THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | VALUE | UNIT |
|---------------|---|-------|------|
| $R_{th\ j-s}$ | thermal resistance from junction to soldering point | 85 | K/W |

General purpose PIN diode

BAP51-02

GRAPHICAL DATA



General purpose PIN diode

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PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD523

DIMENSIONS (mm are the original dimensions)

| UNIT | A | bp | c | D | E | HE | v |
|------|------|------|------|------|------|------|-----|
| mm | 0.65 | 0.34 | 0.17 | 1.25 | 0.85 | 1.65 | 0.1 |
| | 0.58 | 0.26 | 0.11 | 1.15 | 0.75 | 1.55 | |

Note
1. The marking bar indicates the cathode.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|-------|--|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOD523 | | | SC-79 | | | 02-12-13 06-03-16 |

Legal information

Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Revision history

Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------------------------|---|---------------------------|---------------|--------------|
| BAP51-02_N_3 | 20080102 | Product data sheet | - | BAP51-02_2 |
| Modifications: | • Package outline drawing on page 4 changed | | | |
| BAP51-02_2 (9397 750 07151) | 20000706 | Product specification | - | BAP51-02_N_1 |
| BAP51-02_N_1 (9397 750 06152) | 19990628 | Preliminary specification | - | - |



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